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(54) Title: POLISHING PAD WITH A WINDOW

(57) **Abstract:** The present invention relates to a polishing pad. In particular, the polishing pad of the present invention can include a window area. The window area can be formed in the pad using a cast-in-place process. The polishing pad of the present invention can be useful for polishing articles and can be especially useful for chemical mechanical polishing or planarization of a microelectronic device, such as a semiconductor wafer. The window area of the polishing pad of the present invention can be particularly useful for polishing or planarizing tools that are equipped with through-the-platen wafer metrology.

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